

Philips

Diode BAQ800

Datasheet

AM PIN Diode

BAQ800

100V/1.25A

DATASHEET

OEM – Philips

Source: Philips Databook 1999

AM PIN diode**BAQ800****FEATURES**

- Glass passivated
- High maximum operating temperature
- Low leakage current
- Excellent stability
- Available in ammopack.

DESCRIPTION

Cavity free cylindrical glass package through Implotec™⁽¹⁾ technology.
This package is hermetically sealed

and stress free as coefficients of expansion of all used parts are matched.

(1) Implotec is a trademark of Philips.

APPLICATIONS

- RF attenuator with low distortion for frequencies above 100 kHz.

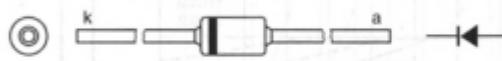


Fig.1 Simplified outline (SOD81) and symbol.

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V_{PRM}	repetitive peak reverse voltage		—	100	V
V_R	continuous reverse voltage		—	100	V
$I_{F(AV)}$	average forward current	$T_{IP} = 25^\circ\text{C}$; lead length = 10 mm; see Fig.2	—	1.25	A
		$T_{amb} = 60^\circ\text{C}$; printed-circuit board mounting (see Fig.17); see Fig.3	—	600	mA
T_{stg}	storage temperature		-65	+175	°C
T_j	junction temperature		-65	+150	°C

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ELECTRICAL CHARACTERISTICS

$T_j = 25^\circ\text{C}$ unless otherwise specified; all characteristics must be tested in the dark because of the light sensitivity of this product.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V_F	forward voltage	$I_F = 100 \text{ mA}$; see Figs 4 and 5	—	0.9	1.1	V
		$I_F = 100 \text{ mA}; T_j = T_{j,\text{max}}$; see Figs 4 and 5	—	0.7	0.9	V
I_R	reverse current	$V_R = 100 \text{ V}$; see Fig.14	—	—	0.1	μA
		$V_R = 100 \text{ V}; T_j = 125^\circ\text{C}$; see Fig.14	—	—	30	μA
τ	charge carrier life time	when switched from $I_F = 10 \text{ mA}$ to $I_R = 6 \text{ mA}$; measured at 10% of I_R ; see Fig.15	10	20	—	μs
C_d	diode capacitance	$f = 1 \text{ MHz}$; see Figs 6, 7, 8 and 9	—	10	12	pF
		$V_R = 0$	—	5	6	pF
r_D	diode forward resistance	$f = 100 \text{ kHz}$; see Figs 10 and 16	—	3100	6000	Ω
		$I_F = 10 \mu\text{A}$	—	380	800	Ω
		$I_F = 100 \mu\text{A}$	—	42	80	Ω
		$I_F = 1 \text{ mA}$	—	5	10	Ω
r_s	diode series resistance	$f = 100 \text{ kHz}$; see Figs 11, 12 and 13	1000	2200	—	k Ω
		$V_R = 0$	5000	11000	—	k Ω
		$V_R = 2 \text{ V}$	25	50	—	k Ω
		$f = 1 \text{ MHz}$; see Figs 11, 12 and 13	100	220	—	k Ω

THERMAL CHARACTERISTICS

All characteristics must be tested in the dark because of the light sensitivity of this product.

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
$R_{th,j-tp}$	thermal resistance from junction to tie-point	lead length = 10 mm	60	K/W
$R_{th,j-a}$	thermal resistance from junction to ambient	note 1	120	K/W

Note

1. Device mounted on an epoxy-glass printed-circuit board, 1.5 mm thick; thickness of Cu-layer $\geq 40 \mu\text{m}$, see Fig.17. For more information please refer to the "General Part of Handbook SC01".

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GRAPHICAL DATA

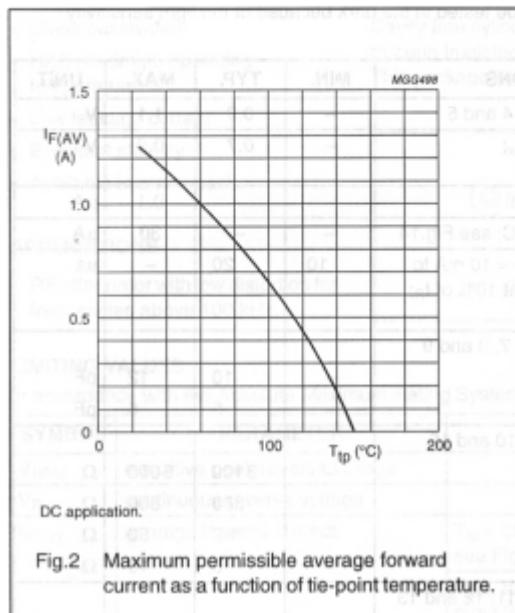


Fig.2 Maximum permissible average forward current as a function of tie-point temperature.

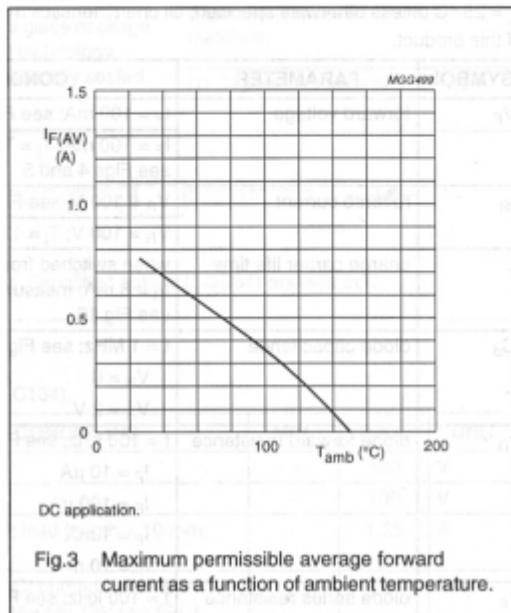


Fig.3 Maximum permissible average forward current as a function of ambient temperature.

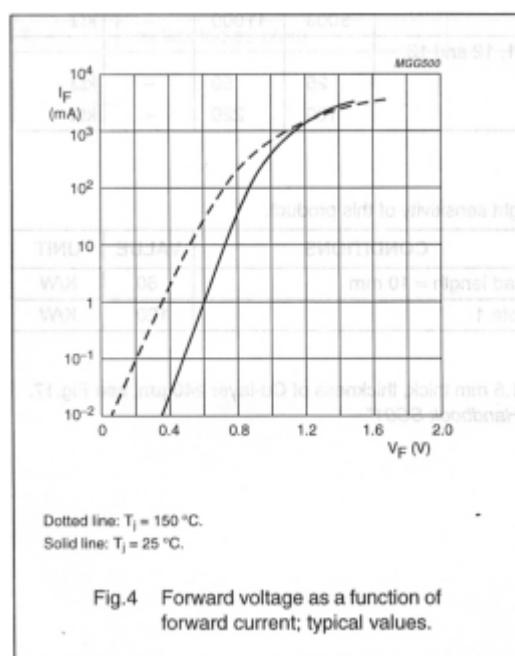


Fig.4 Forward voltage as a function of forward current; typical values.

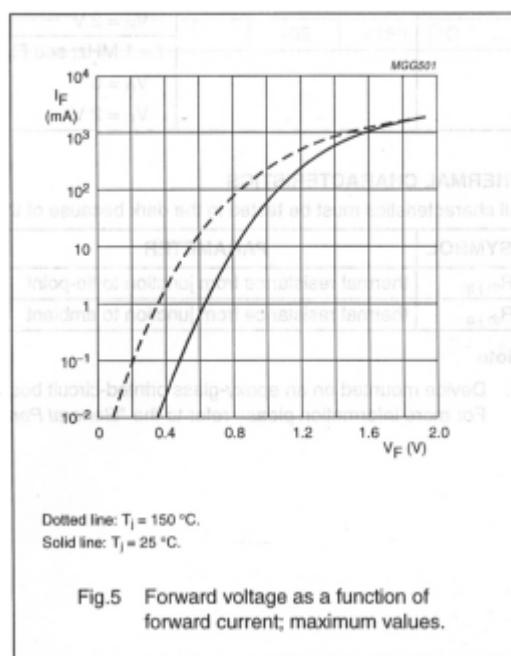
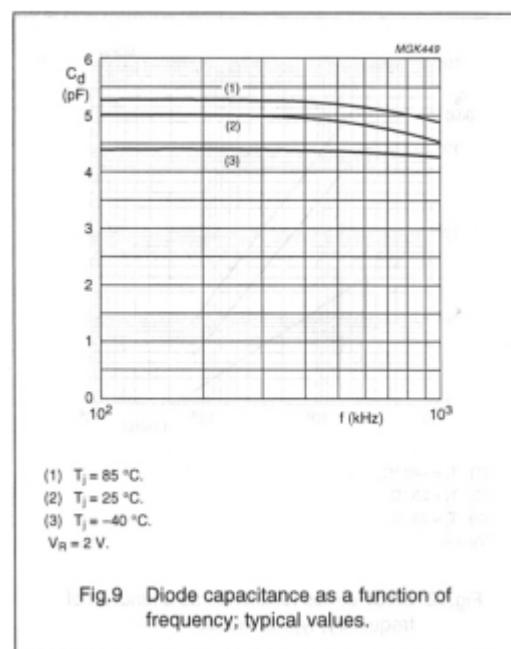
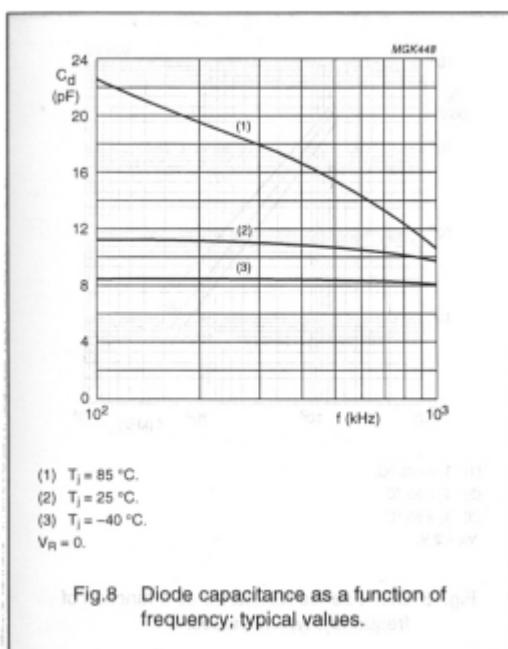
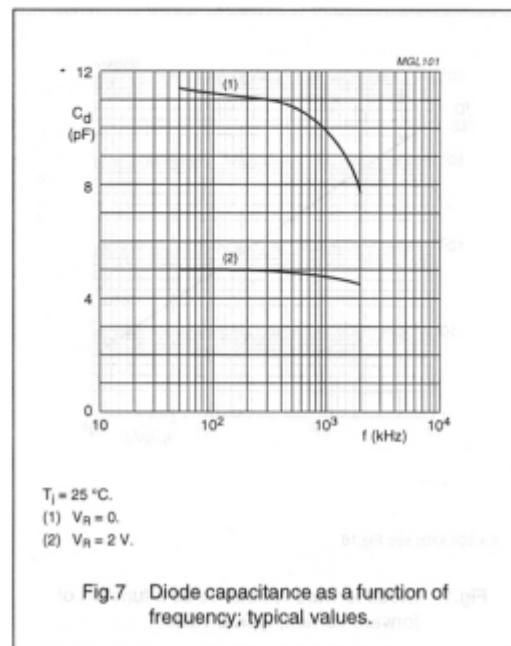
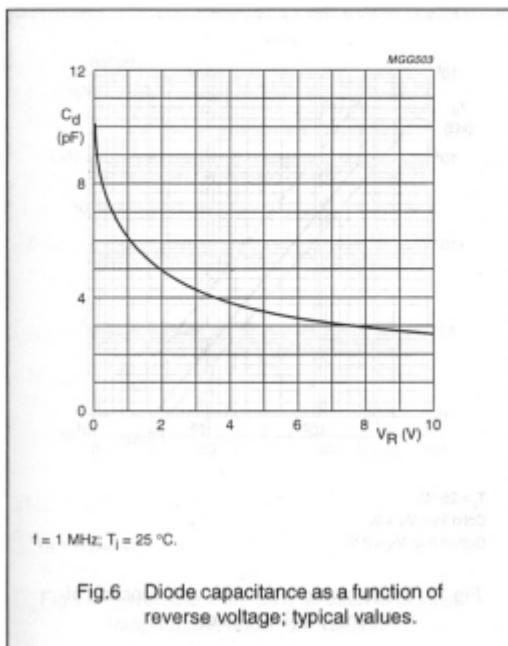


Fig.5 Forward voltage as a function of forward current; maximum values.

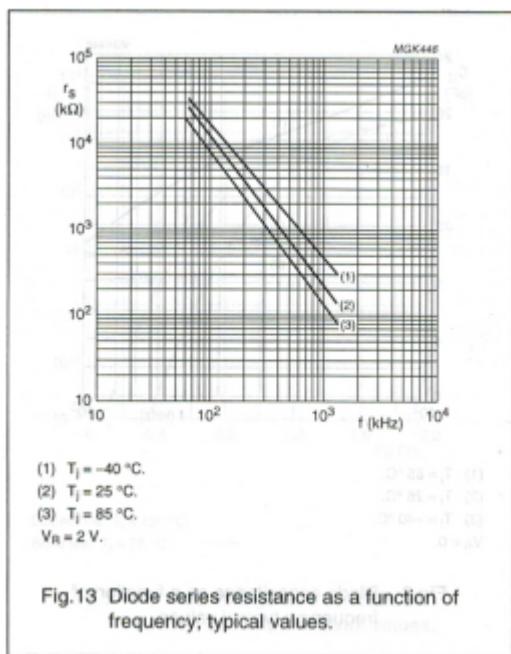
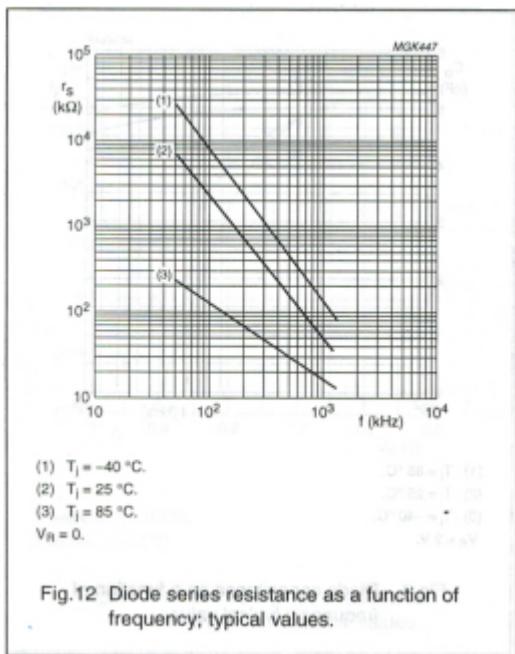
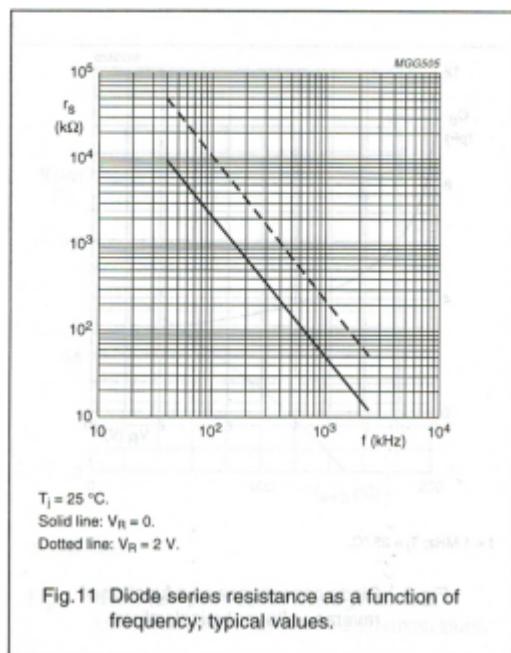
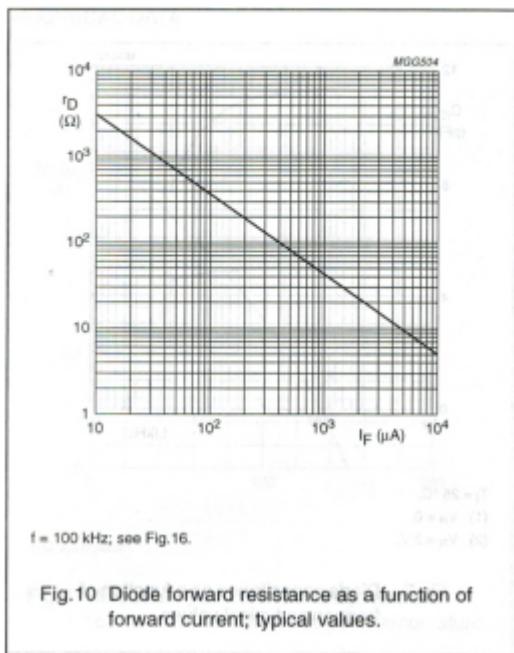
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